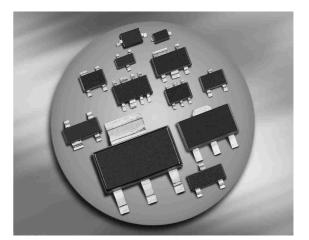


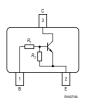
### **NPN Silicon Digital Transistor**

- Switching circuit, inverter, interface circuit, driver circuit
- Built in bias resistor ( $R_1$ =47k $\Omega$ ,  $R_2$ =22k $\Omega$ )
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101





### **BCR146**



Туре	Marking	Pin Configuration				Package		
BCR146	WLs	1=B	2=E	3=C	-	-	-	SOT23

### **Maximum Ratings**

Symbol	Value	Unit	
V <sub>CEO</sub>	50	V	
V <sub>CBO</sub>	50		
V <sub>i(fwd)</sub>	80		
V <sub>i(rev)</sub>	10		
I <sub>C</sub>	70	mA	
P <sub>tot</sub>	200	mW	
T <sub>i</sub>	150	°C	
T <sub>stq</sub>	-65 150		
	$ \begin{array}{c c}     V_{CEO} \\     V_{CBO} \\     V_{i(fwd)} \\     V_{i(rev)} \\     I_C \\     P_{tot} \\     T_j \\   \end{array} $	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	

#### **Thermal Resistance**

Parameter	Symbol	Value	Unit
Junction - soldering point <sup>1)</sup>	R <sub>thJS</sub>	≤ 240	K/W



Parameter	Symbol		Unit			
		min.	typ.	max.		
DC Characteristics			1	1		
Collector-emitter breakdown voltage	V <sub>(BR)CEO</sub>	50	-	-	V	
$I_{\rm C}$ = 100 µA, $I_{\rm B}$ = 0						
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	50	-	-		
$I_{\rm C}$ = 10 µA, $I_{\rm E}$ = 0						
Collector-base cutoff current	I <sub>CBO</sub>	-	-	100	nA	
$V_{\rm CB} = 40 \text{ V}, I_{\rm E} = 0$						
Emitter-base cutoff current	I <sub>EBO</sub>	-	-	220	μA	
$V_{\rm EB} = 10 \text{ V}, I_{\rm C} = 0$						
DC current gain <sup>2)</sup>	h <sub>FE</sub>	50	-	-	-	
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 5 V						
Collector-emitter saturation voltage <sup>2)</sup>	V <sub>CEsat</sub>	-	-	0.3	V	
<i>I</i> <sub>C</sub> = 10 mA, <i>I</i> <sub>B</sub> = 0.5 mA						
Input off voltage	V <sub>i(off)</sub>	1.2	-	2.6		
$I_{\rm C}$ = 100 µA, $V_{\rm CE}$ = 5 V						
Input on voltage	V <sub>i(on)</sub>	1.5	-	4		
$I_{\rm C}$ = 2 mA, $V_{\rm CE}$ = 0.3 V						
Input resistor	<i>R</i> <sub>1</sub>	32	47	62	kΩ	
Resistor ratio	$R_{1}/R_{2}$	1.92	2.14	2.36	-	
AC Characteristics						
Transition frequency	f <sub>T</sub>	-	150	-	MHz	
<i>I</i> <sub>C</sub> = 10 mA, <i>V</i> <sub>CE</sub> = 5 V, <i>f</i> = 100 MHz						
Collector-base capacitance	C <sub>cb</sub>	-	3	-	pF	
V <sub>CB</sub> = 10 V, <i>f</i> = 1 MHz						

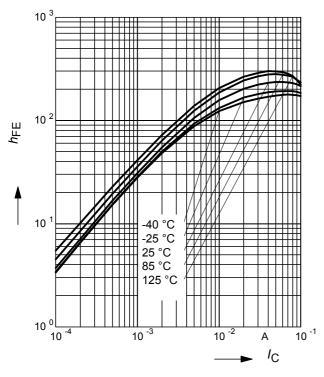
**Electrical Characteristics** at  $T_A = 25^{\circ}$ C, unless otherwise specified

<sup>1</sup>For calculation of  $R_{thJA}$  please refer to Application Note AN077 (Thermal Resistance Calculation) <sup>2</sup>Pulse test: t < 300µs; D < 2%

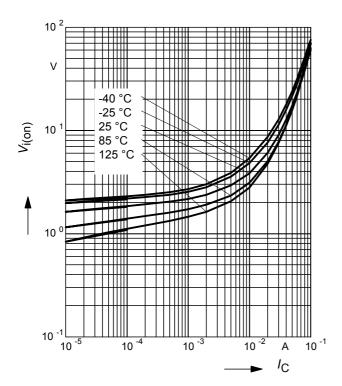


**BCR146** 

## **DC current gain** $h_{FE} = f(I_C)$ $V_{CE} = 5V$ (common emitter configuration)

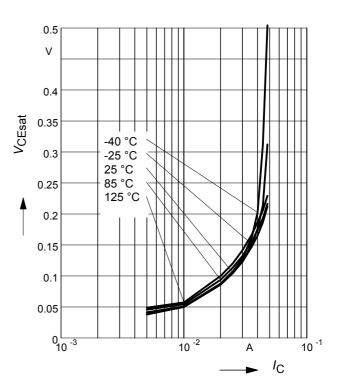


**Input on Voltage**  $V_{i(on)} = f(I_C)$  $V_{CE} = 0.3V$  (common emitter configuration)

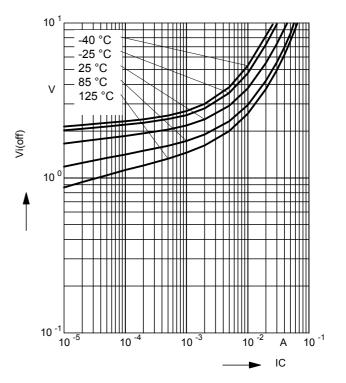


### **Collector-emitter saturation voltage**

 $V_{\text{CEsat}} = f(I_{\text{C}}), I_{\text{C}}/I_{\text{B}} = 20$ 

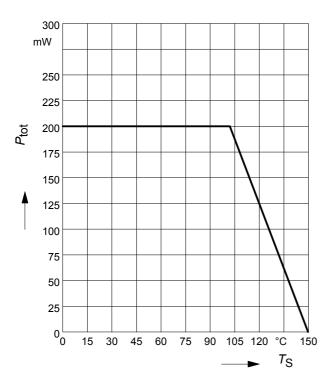


Input off voltage  $V_{i(off)} = f(I_C)$  $V_{CE} = 5V$  (common emitter configuration)

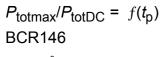


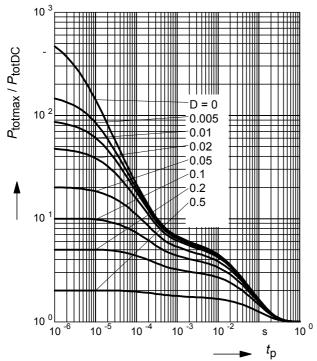


Total power dissipation  $P_{tot} = f(T_S)$ BCR146

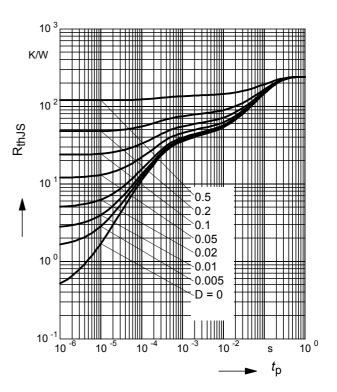


# Permissible Pulse Load



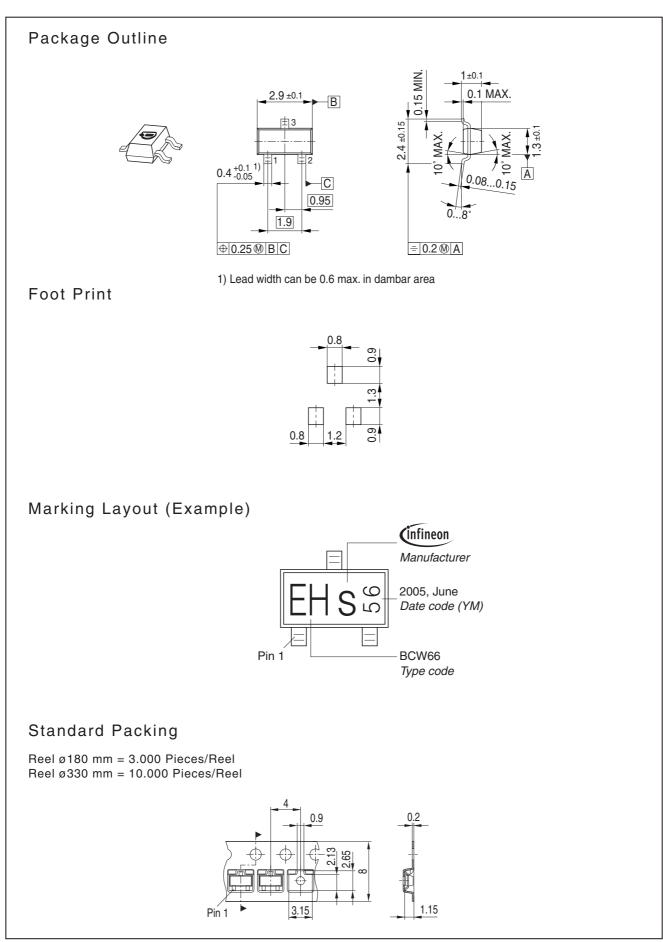


# **Permissible Pulse Load** $R_{\text{thJS}} = f(t_p)$ BCR146





## **BCR146**







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